

5. The method as defined in Claim 1, wherein the grease has:
a thermal conductivity in a range from about 2 Watts/m·K to about 5
Watts/m·K;
a dielectric constant in a range from less than about 6 to about 9; and
a melting point in a range from about 190° C to about 220° C.

6. The method as defined in Claim 1, wherein the IC chip package comprises
IC chip elements, wherein the container disposed upon the substrate encloses a volume
external to the IC chip elements, and wherein the injecting a grease comprises the filling with
the grease of the volume enclosed by the container.

7. The method as defined in Claim 1, wherein the container is in contact with
the active surface of the IC chip.

8. The method as defined in Claim 1, wherein a flip chip is disposed over the
active surface of the IC chip, wherein the container is a dam structure, and wherein the dam
structure is in contact with each of the IC chip, the flip chip, and the grease.

9. The method as defined in Claim 5, wherein the IC chip package comprises
IC chip elements, wherein the container disposed upon the substrate encloses a volume
external to the chip elements, and wherein injecting a grease comprises the filling by the
grease of the volume enclosed by the container.

10. The method as defined in Claim 5, wherein a flip chip is disposed over the
active surface of the IC chip, wherein the container is a dam structure, and wherein the dam
structure is in contact with each of the IC chip, the flip chip, and the grease.

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- 1 12. A method of making an IC chip package having a flip chip with an inactive
2 surface and an active surface, the active surface having extending therefrom an electrical
3 connector in electrical communication with flip chip, the flip chip being mounted upon a
4 substrate, the method comprising:
5 providing a container disposed upon the substrate and in contact with the
6 inactive surface of the flip chip; and
7 injecting a grease between the contact and the substrate so as to contact with
8 the active surface of the flip chip, wherein:
9 the container with the substrate encloses the grease, the electrical
10 connector, and the flip chip;
11 the grease is in contact with the active surface and the electrical
12 connector.
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14 13. The method as defined in Claim 12, further comprising:
15 operating the flip chip to generate heat therefrom;
16 conducting the heat from the flip chip and the electrical connector to the
17 grease, to the container, and to the ambient.
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19 14. The method as defined in Claim 12, wherein the substrate is a flex substrate.
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21 15. The method as defined in Claim 12, wherein the grease has:
22 a thermal conductivity in a range from about 2 Watts/m·K to about 5
23 Watts/m·K;
24 a dielectric constant in a range from less than about 6 to about 9; and
25 a melting point in a range from about 190° C to about 220° C.

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16. A method of making an IC chip package having a first IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with the first IC chip, the first IC chip being mounted upon a first side of a board-on-chip (BOC) substrate having said first side that is opposite a second side thereof, the method comprising:
- providing a second IC chip having an active surface and being disposed over the first side of the BOC substrate;
 - providing a container disposed upon the BOC substrate; and
 - injecting a grease between the BOC substrate and the container;
- wherein the grease:
- is in contact with the electrical connector and with the active surfaces of each of the first and second IC chips; and
 - is enclosed within the container and the substrate.
17. The method as defined in Claim 16, further comprising:
- providing a third IC chip having an active surface and being disposed over the first side of the BOC substrate and over the second IC chip such that the grease is in contact with the active surface of the third IC chip.
18. The method as defined in Claim 16, further comprising:
- operating the first, second, and third IC chips to generate heat therefrom; and
 - conducting the heat from the electrical connector and from the first, second, and third IC chips to the grease, to the container, and to the ambient.

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19. The method as defined in Claim 16, wherein the grease has:
- a thermal conductivity in a range from about 2 Watts/m·K to about 5 Watts/m·K;
- a dielectric constant in a range from less than about 6 to about 9; and
- a melting point in a range from about 190° C to about 220° C.
20. The method as defined in claim 16, further comprising:
- generating heat from at least one of the IC chips by operating said at least one of the IC chips; and
- allowing the heat to propagate to the grease and to the container.